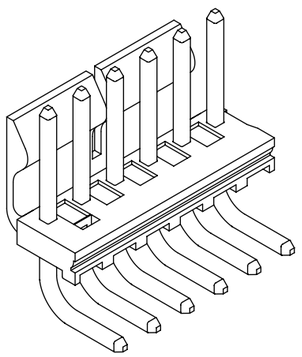
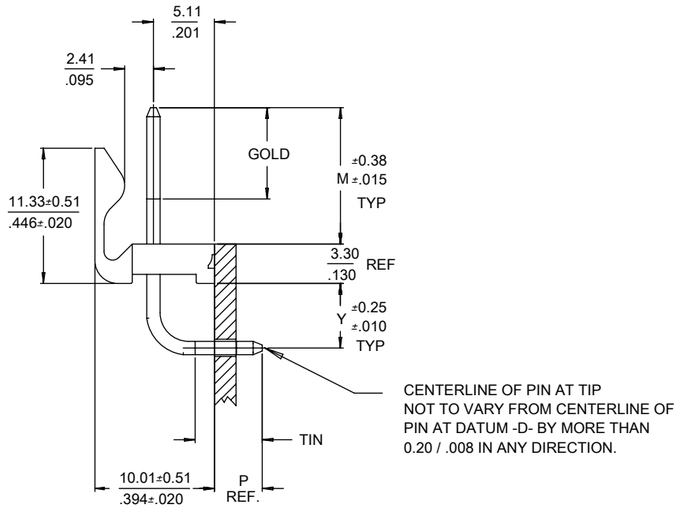
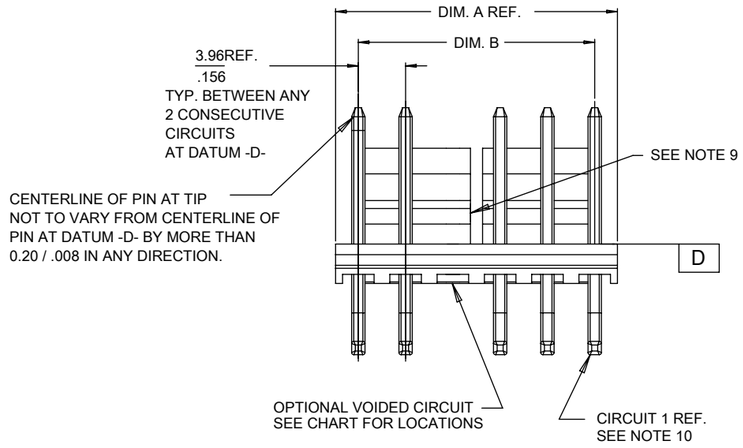
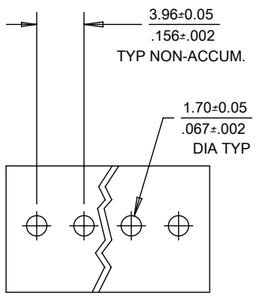






CKT	DIM. A	DIM. B	SLOT LOC BETWEEN CKTS
2	7.77 .306	3.96±0.05 .156±.002	NONE
3	11.73 .462	7.92±0.08 .312±.003	NONE
4	15.70 .618	11.89±0.08 .468±.003	NONE
5	19.66 .774	15.85±0.10 .624±.004	NONE
6	23.62 .930	19.81±0.10 .780±.004	3 & 4
7	27.58 1.086	23.77±0.10 .936±.004	4 & 5
8	31.55 1.242	27.74±0.13 1.092±.005	4 & 5
9	35.51 1.398	31.70±0.13 1.248±.005	5 & 6
10	39.47 1.554	35.66±0.13 1.404±.005	5 & 6
11	43.43 1.710	39.62±0.15 1.560±.006	6 & 7
12	47.40 1.866	43.59±0.15 1.716±.006	4 & 5 8 & 9
13	51.36 2.022	47.55±0.15 1.872±.006	4 & 5 9 & 10
14	55.32 2.178	51.51±0.18 2.028±.007	5 & 6 9 & 10
15	59.28 2.334	55.47±0.18 2.184±.007	5 & 6 10 & 11
16	63.25 2.490	59.44±0.18 2.340±.007	5 & 6 11 & 12
17	67.21 2.646	63.40±0.20 2.496±.008	6 & 7 11 & 12
18	71.17 2.802	67.36±0.20 2.652±.008	6 & 7 12 & 13



PCB LAYOUT: COMPONENT SIDE

NOTES:
1. MATERIAL: HEADER-GLASS FILLED POLYESTER, 94V-0, MOLDED NATURAL (WHITE).
2. FINISH: (197) OVERALL REFLOWED MATTE TIN: 0.00152/.000060 MIN.
   OVER 0.00127/.000050 MIN. NICKEL OVERALL.
   (154) OVERALL TIN: .00254/.000100 MIN OVER .00127/.000050 MIN NICKEL.
   (208) SELECT GOLD: .00038/.000015 MIN, SELECT TIN: .00254/.000100 MIN,
   OVERALL NICKEL UNDERPLATE: .00127/.000050 MIN.
   (228) SELECT GOLD: .00076/.000030 MIN, SELECT TIN: .00254/.000100 MIN,
   OVERALL NICKEL UNDERPLATE: .00127/.000050 MIN.
   (241) SELECT GOLD: 0.00051/.000020 MIN.
   SELECT TIN: 0.00254/.000100 MIN.
   OVERALL NICKEL UNDERPLATE: 0.00127/.000050 MIN.
   FOR ADDITIONAL PLATING INFO, SEE SDES-88.
3. PRODUCT SPECIFICATION AND PROCESS PARAMETERS: SEE PS-08-50.
4. PACKAGING INFORMATION: SEE CHART
5. SOLDERABILITY: PER SMES-152.
6. PIN PUSH-OUT FORCE: PRIOR TO SOLDERING, A 3 LB. MINIMUM FORCE (IN EITHER DIRECTION)
7. PARTS ARE STACKABLE END TO END ON 3.96/.156 CENTERS.
8. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.
9. SLOTS ON BACKWALL ARE BETWEEN CIRCUITS. SEE CHART FOR LOCATION.
10. CIRCUIT 1 DESIGNATION IS USED TO DEFINE VOID LOCATION. CIRCUIT 1 MAY OR MAY NOT LINE UP WITH CIRCUIT 1 ON THE MATING HOUSING.

Model: EM-41792 (SD Package)

RELEASE STATUS		RELEASE DATE	

QUALITY SYMBOLS
E/A = 0
E/C = 0
E/B = 0
= 0
C = 0
= 0
= 0
= 0

EC NO: 112230 2017/01/10
DRWN: MKIPPER 2017/01/19
CHK'D: JDFOX 2017/01/30
APPR: FSMITH
ADD 41792-0704
REV K4

GENERAL TOLERANCES (UNLESS SPECIFIED)

	MM	INCH
4 PLACES	±	±
3 PLACES	±	± 0.01
2 PLACES	± 0.25	± 0.015
1 PLACES	± 0.38	±
0 PLACES	±	±

ANGULAR TOL ± 0.5

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION UNITS: MM/IN
SCALE: 2:1
DRWN BY: JSCHAFER DATE: 11-07-03
CHK'D BY: KSAMIEC DATE: 11-10-03
APPR BY: MARGULIS DATE: 11-17-03
DRAWING SIZE: B
THIRD ANGLE PROJECTION

molex®

KK .156 HEADER ASSEMBLY
FRICTION LOCK RIGHT ANGLE W/O PEGS

PRODUCT CUSTOMER DRAWING

SERIES	MATERIAL NUMBER	CUSTOMER
41792	SEE CHART	GENERAL MARKET

DOCUMENT NUMBER	DOC TYPE	DOC PART	SHEET NUMBER
SDA-41792	PSD	000	1 OF *

FORMAT: Eng-lega-master-tb-prod-B
REVISION: C
DATE: 2016/04/04